

FUJI POWER MOSFET

Super FAP-G Series

N-CHANNEL SILICON POWER MOSFET

Features

- High speed switching
- Low on-resistance
- No secondary breakdown
- Low driving power
- Avalanche-proof

Applications

- Switching regulators
- UPS (Uninterruptible Power Supply)
- DC-DC converters

Maximum ratings and characteristic Absolute maximum ratings

($T_c=25^\circ\text{C}$ unless otherwise specified)

Item	Symbol	Ratings	Unit
Drain-source voltage	V_{DS}	450	V
Continuous drain current	I_D	± 3	A
Pulsed drain current	$I_{D(puls)}$	± 12	A
Gate-source voltage	V_{GS}	± 30	V
Repetitive or non-repetitive	I_{AR} *2	3	A
Maximum Avalanche Energy	EAS *1	92.8	mJ
Maximum Drain-Source dV/dt	dV _{DS} /dt *4	20	kV/ μs
Peak Diode Recovery dV/dt	dV/dt *3	5	kV/ μs
Max. power dissipation	P_D	$T_a=25^\circ\text{C}$	2.02
		$T_c=25^\circ\text{C}$	50
Operating and storage temperature range	T_{ch}	+150	$^\circ\text{C}$
	T_{stg}	-55 to +150	$^\circ\text{C}$

*1 $L=18.9\text{mH}$, $V_{CC}=45\text{V}$, $T_{ch}=25^\circ\text{C}$ See to Avalanche Energy Graph *2 $T_{ch}\leq 150^\circ\text{C}$

*3 $I_F\leq -I_D$, $-di/dt=50\text{A}/\mu\text{s}$, $V_{CC}\leq BV_{DS}$, $T_{ch}\leq 150^\circ\text{C}$ *4 $V_{DS}\leq 450\text{V}$

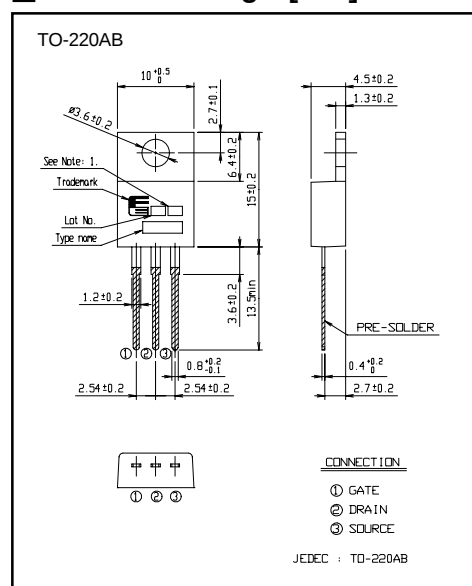
Electrical characteristics ($T_c=25^\circ\text{C}$ unless otherwise specified)

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D=250\mu\text{A}$ $V_{GS}=0\text{V}$	450			V
Gate threshold voltage	$V_{GS(th)}$	$I_D=250\mu\text{A}$ $V_{DS}=V_{GS}$	3.0		5.0	V
Zero gate voltage drain current	I_{DSS}	$V_{DS}=450\text{V}$ $V_{GS}=0\text{V}$ $T_{ch}=25^\circ\text{C}$			25	μA
		$V_{DS}=360\text{V}$ $V_{GS}=0\text{V}$ $T_{ch}=125^\circ\text{C}$			250	
Gate-source leakage current	I_{GSS}	$V_{GS}=\pm 30\text{V}$ $V_{DS}=0\text{V}$			100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$I_D=1.5\text{A}$ $V_{GS}=10\text{V}$		1.92	2.50	Ω
Forward transconductance	g_{fs}	$I_D=1.5\text{A}$ $V_{DS}=25\text{V}$	1.25	2.5		S
Input capacitance	C_{iss}	$V_{DS}=25\text{V}$		235	355	pF
Output capacitance	C_{oss}	$V_{GS}=0\text{V}$		42	65	
Reverse transfer capacitance	C_{rss}	$f=1\text{MHz}$		2	3	
Turn-on time t_{on}	$t_{d(on)}$	$V_{CC}=300\text{V}$ $I_D=1.5\text{A}$		16	24	ns
	t_r	$V_{GS}=10\text{V}$		4	6	
Turn-off time t_{off}	$t_{d(off)}$	$R_{GS}=10\Omega$		23	35	
	t_f			6	9	
Total Gate Charge	Q_G	$V_{CC}=225\text{V}$		10.5	16	nC
Gate-Source Charge	Q_{GS}	$I_D=3\text{A}$		5.5	8.3	
Gate-Drain Charge	Q_{GD}	$V_{GS}=10\text{V}$		1.0	1.5	
Avalanche capability	I_{AV}	$L=18.9\text{mH}$ $T_{ch}=25^\circ\text{C}$	3			A
Diode forward on-voltage	V_{SD}	$I_F=3\text{A}$ $V_{GS}=0\text{V}$ $T_{ch}=25^\circ\text{C}$		1.00	1.50	V
Reverse recovery time	t_{rr}	$I_F=3\text{A}$ $V_{GS}=0\text{V}$		0.28		μs
Reverse recovery charge	Q_{rr}	$-di/dt=100\text{A}/\mu\text{s}$ $T_{ch}=25^\circ\text{C}$		1.4		μC

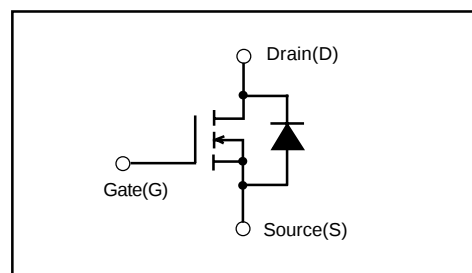
Thermal characteristics

Item	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Thermal resistance	$R_{th(ch-c)}$	channel to case			2.5	$^\circ\text{C}/\text{W}$
	$R_{th(ch-a)}$	channel to ambient			62.0	$^\circ\text{C}/\text{W}$

Outline Drawings [mm]



Equivalent circuit schematic



Characteristics

